| ABSOCIATION CONNECTING<br>ELECTRONICS (NOUSTRIES+)<br>international and Pan-American | kburn, Illinois. A  | Il rights reserved u ntions. | nder both           | This docume<br>level parts, t | ent is a declara<br>he declaration                               | tion of the sencompass | substances<br>es all low | s within the manufactu<br>er level materials for v | arer listed which the           | item. Note: i<br>manufacture | f the item is an as<br>r has engineering | sembly with lower responsibility.     |  |
|--|---|------------------------------|---------------------|-------------------------------|--|------------------------|--------------------------|--|---------------------------------|------------------------------|--|---------------------------------------|--|
|  | IPC Web Site for Information on IPC-1752 Standard Form Typ   http://www.ipc.org/IPC-175x Distribute |                              |                     | *                             | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materi |                        |                          |  |                                 | als and Mfg Information      |  |                                       |  |
| Supplier Information   |   |                              |                     |                               |  |                        |                          |  |                                 |                              |  |                                       |  |
| Company name* Company unique ID  |   |                              | Unique ID Authority |                               |  |                        | Response Date*           |  |                                 |                              |  |                                       |  |
| nsemi  |   |                              |                     |                               |  |                        |                          |  | 2023-06-08                      |                              |  |                                       |  |
| Contact Name   | tact Name Title - Contact   |                              |                     | 1                             | Phone - Contact*   |                        |                          |  | Email                           | Email - Contact*             |  |                                       |  |
| oduct-Env-Stewards Product Enviro Compliance   |   |                              |                     | NA                            |  |                        |                          | Produ  | Product-Env-Stewards@onsemi.com |                              |  |                                       |  |
| uthorized Representative* Title - Representative                                     |   |                              |                     | Phone - Representative*       |  |                        |                          | Email  | Email - Representative*         |                              |  |                                       |  |
| Product-Env-Stewards Product Enviro Compliance                                       |   |                              |                     | NA                            |  |                        |                          | Product-Env-Stewards@onsemi.com                    |                                 |                              |  |                                       |  |
| Requester Item Number Mfr It   | Number Mfr Item Number  |                              | Mfr Item Name       |                               | Effective Dat  | e Version              | 1                        | Manufacturing Site                                 |                                 | Weight*                      | UOM                                      | Unit Type                             |  |
| FL51:  | 0MX   | MX AC Dimmer Cntlr fo        |                     |                               | 2023-06-08   | TAD                    |                          |  | 77.8214                         | mg                           | Each                                     |                                       |  |
| Manufacturing Proccess Information   |   |                              |                     |                               |  |                        |                          |  |                                 |                              |  | · · · · · · · · · · · · · · · · · · · |  |
| Terminal Plating / Grid Array Material   | ting / Grid Array Material Terminal Base Alloy J  |                              | -STD-020 MSL        | Rating                        | Peak Pro   | cess Body 7            | Femperatu                | re Max Time at Peal                                | k Tempera                       | ture Numb                    | per of Reflow Cyc                        | cles                                  |  |
| Matte Tin (Sn) - annealed CU Alloy 1   |   |                              | l                   |                               | 260  |                        | С                        | 30   | seco                            | nds 3                        |  |                                       |  |
| Comments   |   |                              |                     |                               |  |                        |                          |  |                                 |                              |  |                                       |  |
| level 1 - maximum time at peak temperature during                                    | soldering is 10-3   | 0 seconds                    |                     |                               |  |                        |                          |  |                                 |                              |  |                                       |  |
| For more information regarding material compositi                                    | on please refer to  | page 3                       |                     |                               |  |                        |                          |  |                                 |                              |  |                                       |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight  | Unit of Measure | Level    | Substance               | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|---------|-----------------|----------|-------------------------|------------------|--------|---------|-----------------|
| Die                  | 1.43    | mg              | Supplier | Silicon (Si)            | 7440-21-3        |        | 1.43    | mg              |
| Die Attach           | 0.0631  | mg              |          | Epoxy resin             | proprietary data |        | 0.0063  | mg              |
|                      |         |                 | Supplier | Silver (Ag)             | 7440-22-4        |        | 0.0505  | mg              |
|                      |         |                 | Supplier | Formaldehyde Polymer    | 9003-36-5        |        | 0.0063  | mg              |
| Lead Frame           | 25.2775 | mg              | Supplier | Silver (Ag)             | 7440-22-4        |        | 0.0202  | mg              |
|                      |         |                 | Supplier | Zinc (Zn)               | 7440-66-6        |        | 0.0506  | mg              |
|                      |         |                 | Supplier | Iron (Fe)               | 7439-89-6        |        | 0.632   | mg              |
|                      |         |                 | Supplier | Copper (Cu)             | 7440-50-8        |        | 24.5494 | mg              |
|                      |         |                 | Supplier | Phosphorus (P)          | 7723-14-0        |        | 0.0253  | mg              |
| Mold Compound-Black  | 48.6018 | mg              |          | Epoxy resin             | proprietary data |        | 3.4021  | mg              |
|                      |         |                 | Supplier | Phenolic Resin          | Proprietary Data |        | 1.4581  | mg              |
|                      |         |                 | Supplier | Silica Amorphous (SiO2) | 7631-86-9        |        | 4.8602  | mg              |
|                      |         |                 | Supplier | Carbon Black (C)        | 1333-86-4        |        | 0.243   | mg              |
|                      |         |                 | Supplier | Fused Silica (SiO2)     | 60676-86-0       |        | 38.6384 | mg              |
| Plating              | 2.37    | mg              | Supplier | Tin (Sn)                | 7440-31-5        |        | 2.37    | mg              |
| Wire Bond - Au       | 0.079   | mg              | Supplier | Gold (Au)               | 7440-57-5        |        | 0.079   | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).